

High Power LED  
5050

5044 RGBW Series  
Full Color

For Outdoor Lighting

#### Features & Benefits

- 20.0 W class high power LED
- Mold resin for high reliability
- Standard form factor for design flexibility (5.0 × 5.0 mm)

DESIGN

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## 1. Characteristics

### a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	$T_a$	-40 ~ +105	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +105	°C	-
LED Junction Temperature	$T_j$	125	°C	-
Forward Current	$I_F$	R 1000*1 GBW 1500*3	mA	-
Pulse Forward Current	$I_{FP}$	R 1500 GBW 2000	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	1	kV	-

b) Electro-optical Characteristics ( $I_F = 350 \text{ mA}$ ,  $T_s = 25^\circ\text{C}$ )

Item	Unit	Rank	Color	Min.	Typ.	Max.
Forward Voltage ( $V_F$ )	V	V0	Red	2.0	-	2.4
			Green	2.6	-	3.0
			Blue	2.8	-	3.2
			White	2.8	-	3.2
Dominant wavelength ( $\lambda_D$ )	nm	000	Red	615	-	625
			Green	520	-	530
			Blue	445	-	455
Peak wavelength ( $\lambda_P$ )	nm		Red	-	628	-
			Green	-	518	-
			Blue	-	447	-
Color Rendering Index ( $R_a$ )	-		White	80	-	-
Color Temperature(CCT)	K		White	3200	-	3600
Luminous Flux ( $\Phi_v$ )	lm	00	Red	90	-	100
			Green	140	-	160
			Blue	20	-	26
			White	160	-	180
Thermal Resistance (junction to solder point)	$^\circ\text{C/W}$			-	5	-
Beam Angle	$^\circ$			-	120	-

Note:

 Ledstar maintains measurement tolerance of: Luminous Intensity =  $\pm 7\%$ , forward voltage =  $\pm 0.1 \text{ V}$ , Wavelength =  $\pm 2 \text{ nm}$ , CRI =  $\pm 3$

## 2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	
L	D	R	-	5	0	5	0	C	N	F	R	G	B	W	-	V	0	0	0	0	0

Digit	PKG Information	Code	Specification
1 2 3	Ledstar Package Middle Power	LDR	
4 5 6 7	Package Model and Size	5050	5.15 x 5.15 x 2.80mm
8	Product Category	C	Ceramics
9	Bractek Type	N	AIN
10	Version	F	
11 12 13	Color	RGB	Full Color
14	Serial Number	W	White
15 16	Forward Voltage (V)	V0	B0 2.0~2.2 C0 2.2~2.4 Bin Code: E0 2.6~2.8 F0 2.8~3.0 G0 3.0~3.2
17 18 19	Dominant Wavelength (nm)	000	
20 21	Luminous Flux (lm)	00	

**a) Voltage Bins ( $I_F = 350\text{mA}$ ,  $T_S = 25^\circ\text{C}$ )**

Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
LDR-5050CNFRGBW-V000000	V0	B0	2.0 ~ 2.2
		C0	2.2 ~ 2.4
		E0	2.6 ~ 2.8
		F0	2.8 ~ 3.0
		G0	3.0 ~ 3.2

**b) Wavelength Bins ( $I_F = 350\text{ mA}$ ,  $T_S = 25^\circ\text{C}$ )**

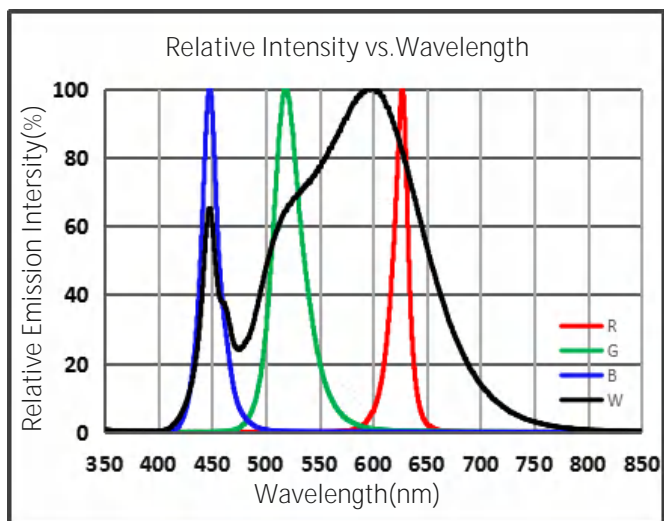
Product Code	Wavelength Rank	Color	Wavelength Bin	Wavelength Range/ TC (nm) (K)
LDR-5050CNFRGBW-V000000	000	Red	UR1	615 ~ 620
			UR2	620 ~ 625
		Green	EG2	520 ~ 525
			EG3	525 ~ 530
		Blue	UB1	445 ~ 450
			UB2	450 ~ 455
		White		3200 ~ 3600

**c) Luminous Intensity Bins ( $I_F = 350\text{ mA}$ ,  $T_S = 25^\circ\text{C}$ )**

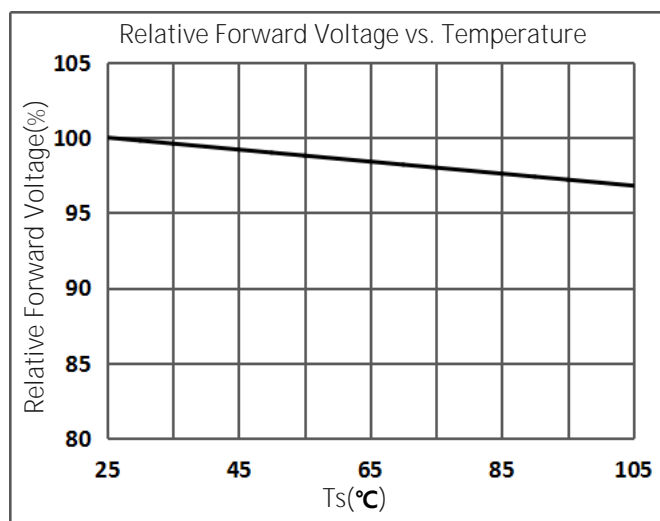
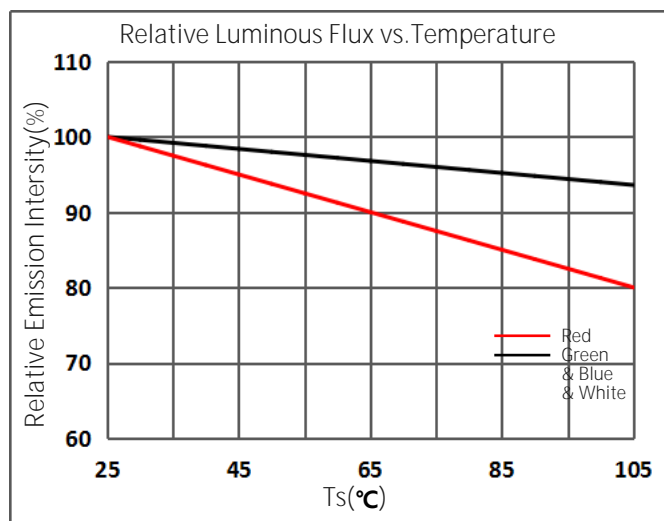
Product Code	Flux Rank	Color	Flux Range ( $\Phi_v$ , lm)
LDR-5050CNFRGBW-V000000	00	Red	90 ~ 100
		Green	140 ~ 160
		Blue	20 ~ 26
		White	160 ~ 180

### 3. Typical Characteristics Graphs

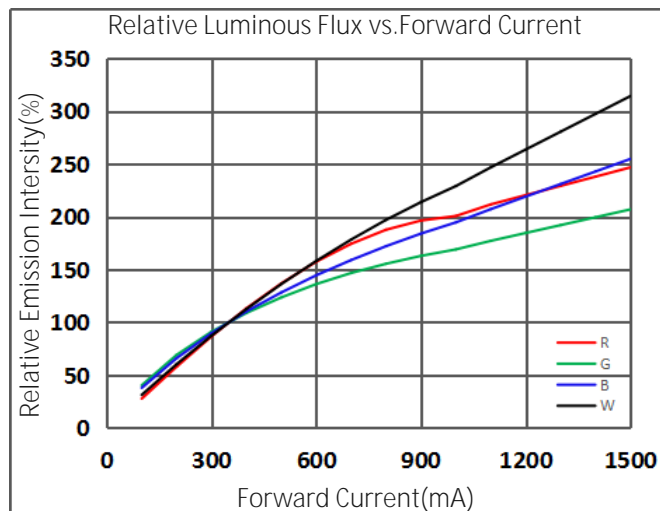
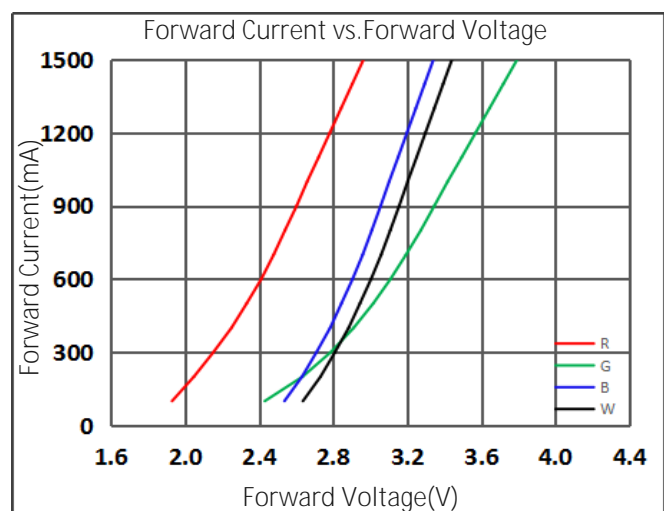
#### a) Spectrum Distribution ( $I_F = 350\text{mA}$ , $T_s = 25^\circ\text{C}$ )



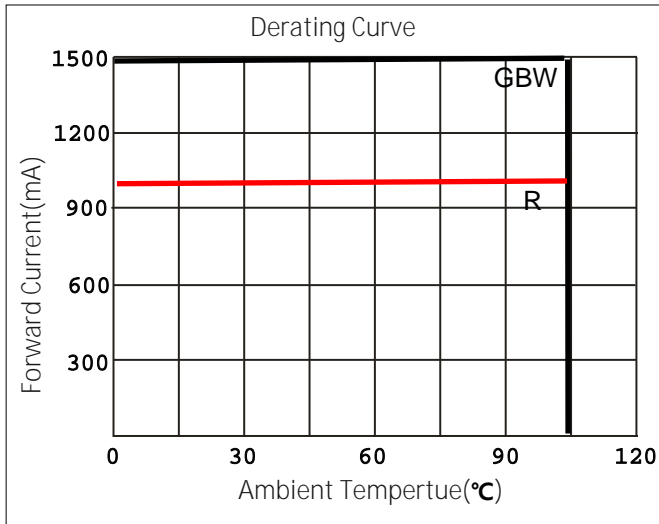
#### b) Temperature Characteristics ( $I_F = 350\text{mA}$ )



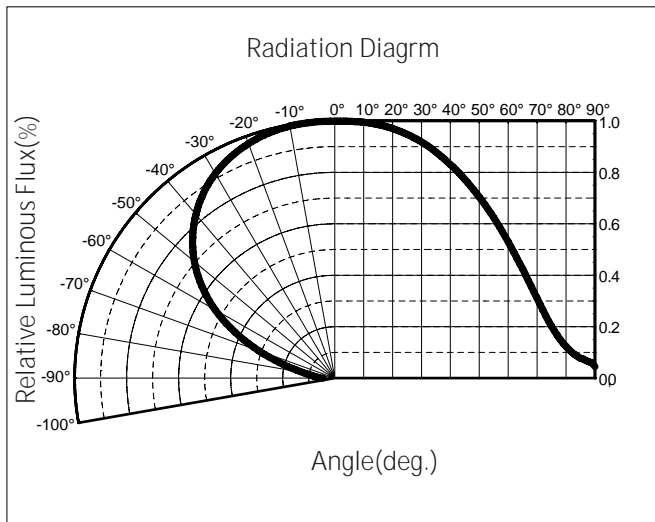
#### c) Forward Current Characteristics ( $T_s = 25^\circ\text{C}$ )



d) Derating Curve

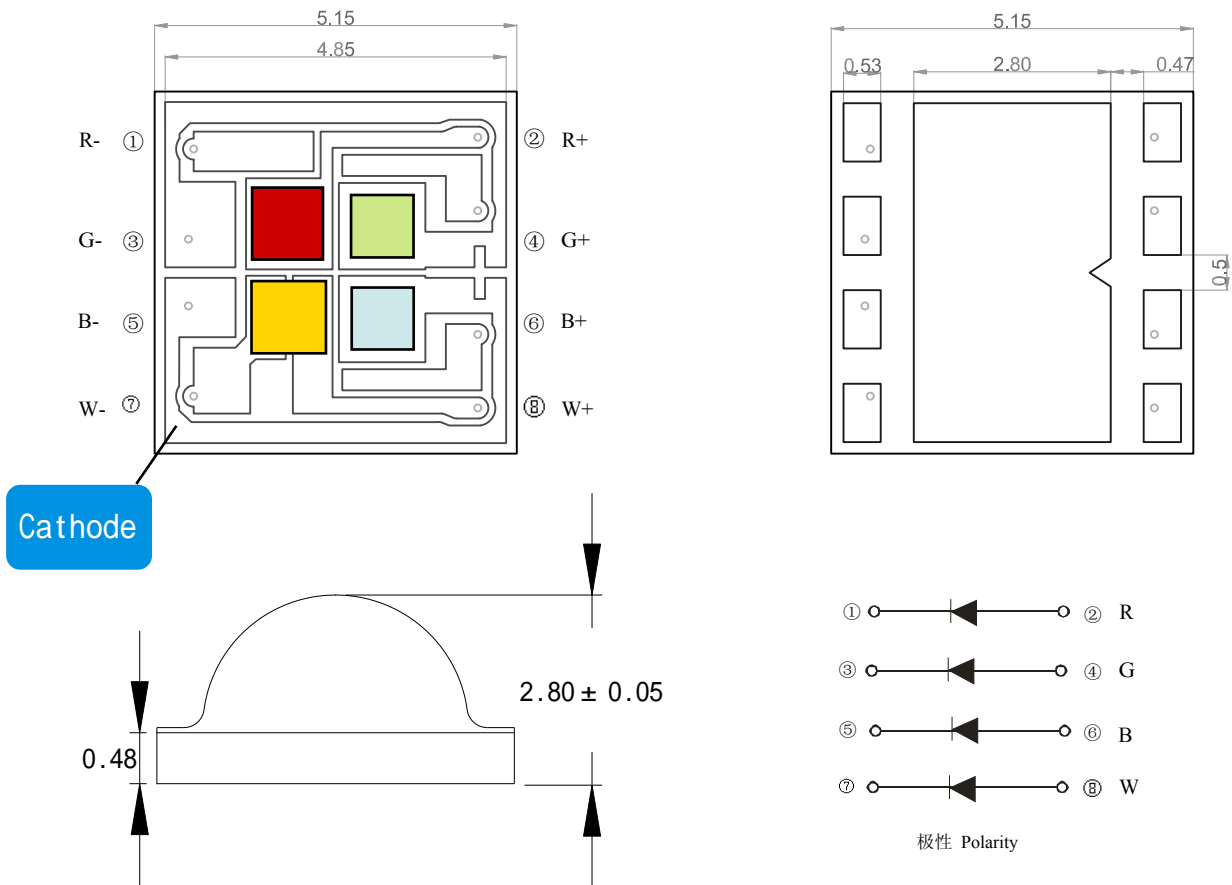


e) Beam Angle Characteristics ( $T_s = 25^{\circ}\text{C}$ )





#### 4. Outline Drawing & Dimension



Notes:

$T_s$  point and measurement method:

- ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach  $T_s$  point.
- ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.
- ③ All dimensions in mm. Tolerances unless mentioned is  $\pm 0.1$  mm.

Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

### a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
Room Temperature Life Test	25°C DC R 1000,GBW 1500mA	1000 h	22
High Temperature Life Test	85°C, DC R 1000,GBW 1500mA	1000 h	22
High Temperature Humidity Life Test	85°C, 85 % RH, DC R 1000,GBW 1500mA	1000 h	22
Low Temperature Life Test	-40°C, DC R 1000,GBW 1500mA	1000 h	22
Powered Temperature Cycle Test	-40 °C ~ 85°C, each 10 min, On/Off 5min , Temp. Change Time 20min, DC R 1000,GBW 1500mA	100 cycles	22
Thermal Cycle	-40°C / 15 min ↔ 105°C / 15 min → Hot plate 180°C	100 cycles	100
High Temperature Storage	105°C	1000 h	22
Low Temperature Storage	-40°C	1000 h	22

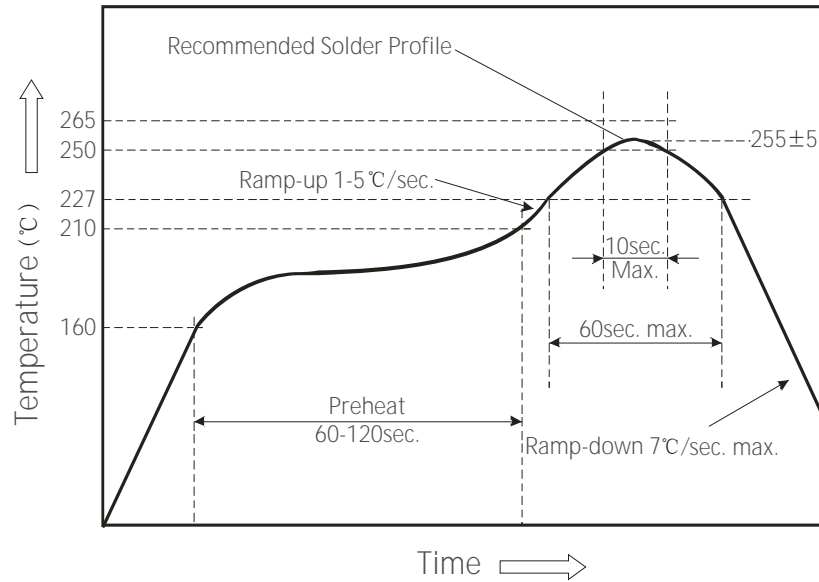
### b) Criteria for Judging the Damage

Item	Symbol	Test Condition (Ts = 25°C)	Limit	
			Min	Max
Forward Voltage	$V_F$	$I_F = R\ 1000, BGW\ 1500\ mA$	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	$\Phi_v$	$I_F = R\ 1000, BGW\ 1500\ mA$	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

### a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



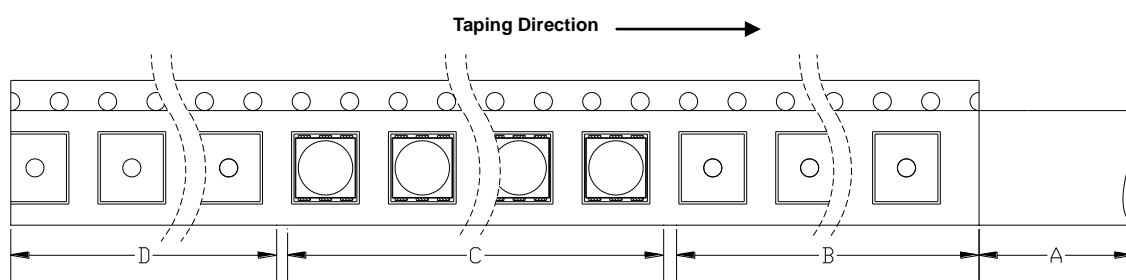
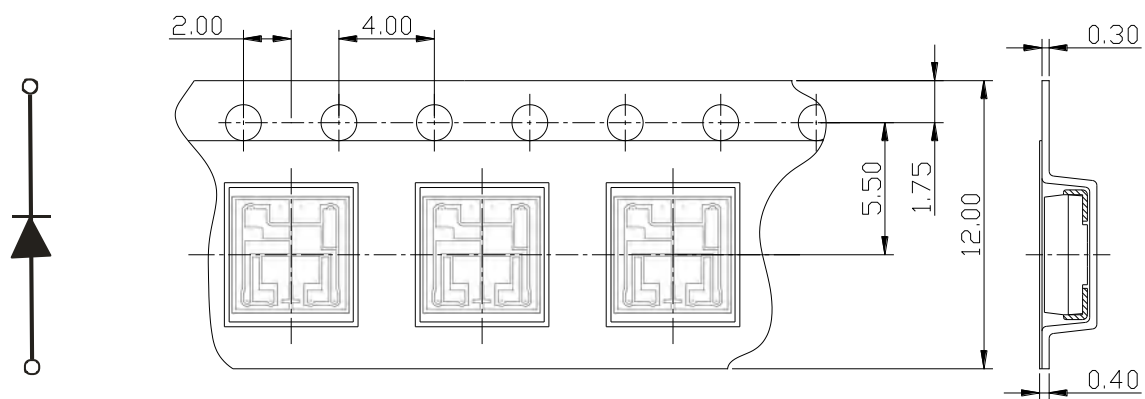
### b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300°C, under soldering iron.

## 7. Tape & Reel

### a) Taping Dimension

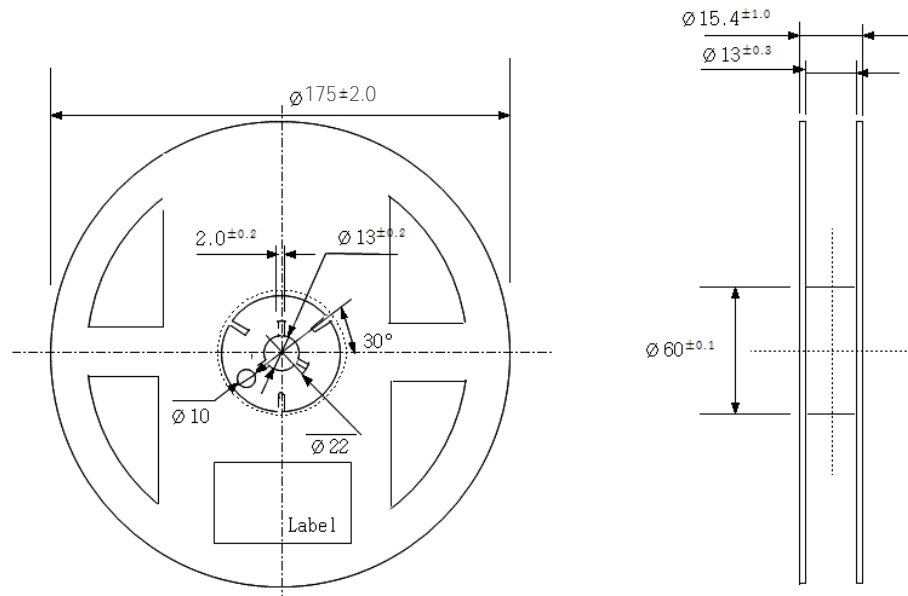
(unit: mm)



A: Top Cover Tape, 300mm; B: Leader, Empty, 200mm; C: 1000 Lamps Loaded; D: Trailer, Empty, 200mm.

## b) Reel Dimension

(unit: mm)



### Notes:

- 1) Quantity: The quantity/reel is 1,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is  $\pm 0.2$  mm
- 3) Adhesion Strength of Cover Tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at  $10^\circ$  angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## 8. Label Structure

### a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

### b) Label Explannation

Part No.:Product Code

IF:Testing Current

VF:Forward Voltage Range

IV:Luminous Flux Range

WLD:Wavelength Range

Date:Packing Date

Bin:Rank

C/N:Internal Identification Code

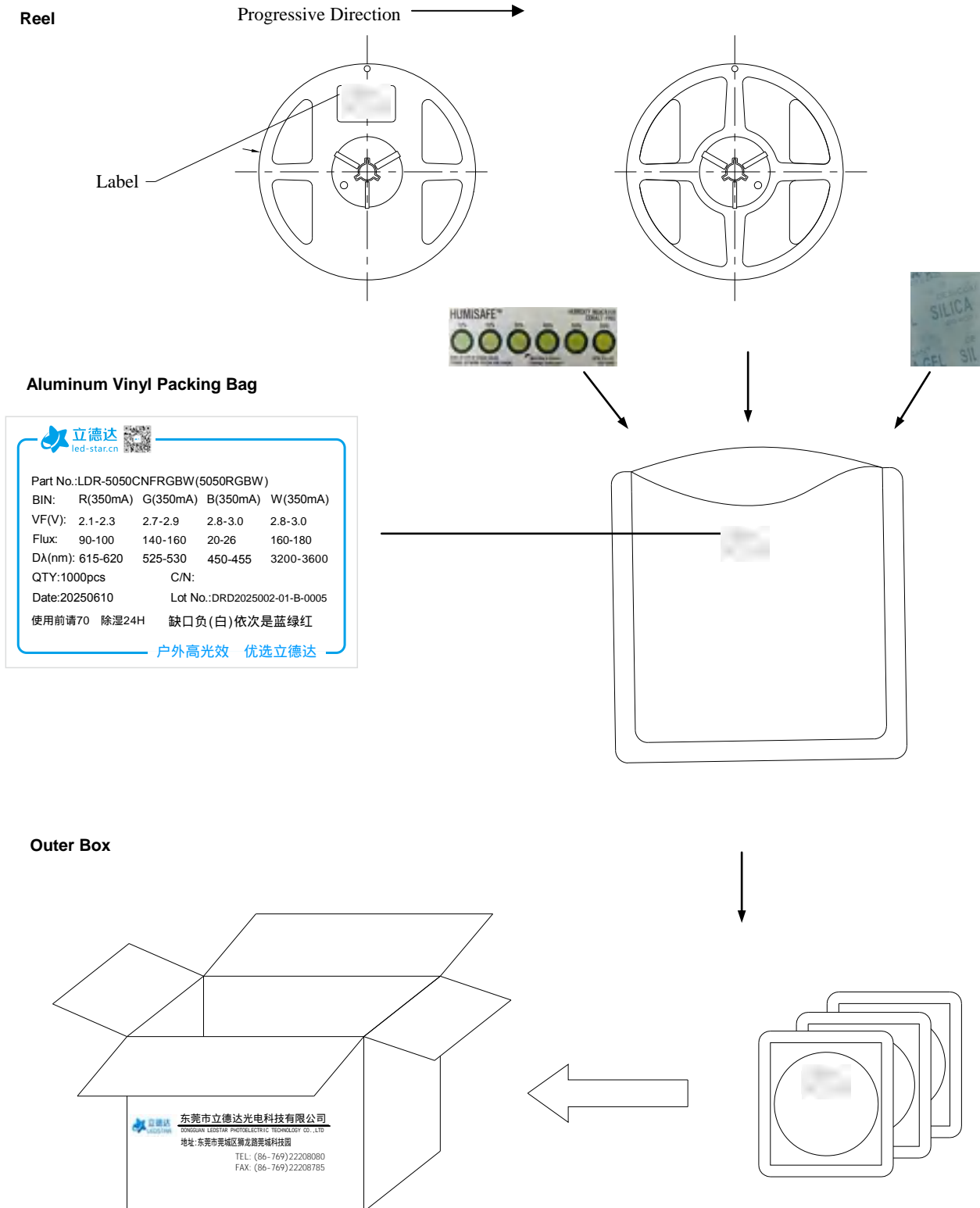
Remark:Special Remark

QTY:Quantity

Lot No.:Production batch Number

## 9. Packing Structure

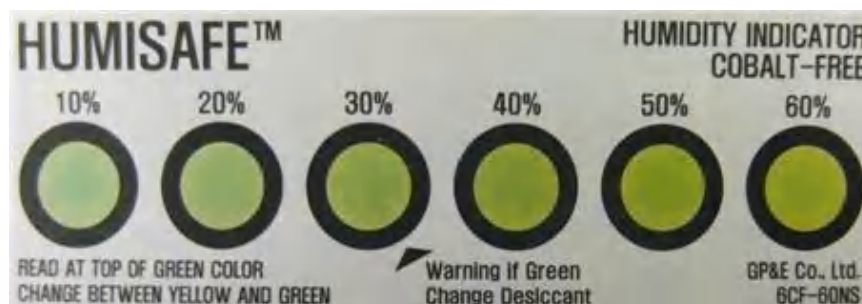
### a) Packing Process (The quantity of PKG on the Reel to be Max 1,000pcs)



## b) Aluminum Vinyl Packing Bag



## c) Silica Gel &amp; Humidity Indicator Card inside Aluminum Vinyl Bag





## 10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Ledstar, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
  - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH<sup>\*Note 1</sup>, or
  - b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH<sup>\*Note 2</sup>, or
  - c. Stored at <10 % RH.

\*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

Package Type and Body Thickness	Moisture Sensitivity Level	Maximum Percent Relative Humidity						Temperature
		40%	50%	60%	70%	80%	90%	
Body Thickness <2.1mm	Level 2a	∞	∞	28	1	1	1	30°C
		∞	∞	∞	2	1	1	25°C
		∞	∞	∞	2	2	1	20°C

- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 8) Devices must be baked for 10~24 hours at 70 ± 5 °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)
 

The LED from Ledstar uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.